



**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

Form PTO-1449 (Modified)
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COMPLETE IF KNOWN

Application Number	09/885,232
Confirmation Number	4989
Filing Date	06/20/2001
First Named Inventor	LinLin Chen
Group Art Unit	1741
Examiner Name	Unknown
Attorney Docket No.	29195-8163US2

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U.S. PATENT DOCUMENTS

Examiner Initials	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Figures Appear
		NUMBER	Kind Code (if known)			
lll.		09/738,551		Morrissey et al.	01/03/02	<div>RECEIVED DEC 23 2003 TC 1700 MAIL ROOM</div>
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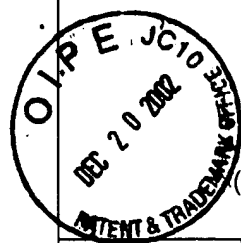
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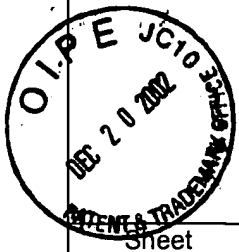
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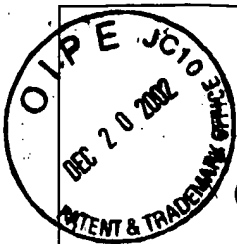
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* * No date avail

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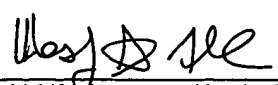
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